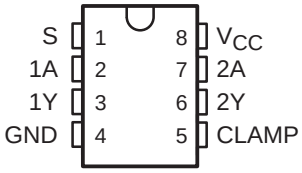
- **Characterized for Use to 300 mA**
- **No Output Latch-Up at 55 V (After Conducting 300 mA)**
- **High-Voltage Outputs (100 V Typ)**
- **Output Clamp Diodes for Transient Suppression (300 mA, 70 V)**
- **TTL- or MOS-Compatible Diode-Clamped Inputs**
- **pnp Transistor Inputs Reduce Input Current**
- **Standard Supply Voltage**
- **Suitable for Hammer-Driver Applications**
- **Plastic DIP (P) With Copper-Lead Frame Provides Cooler Operation and Improved Reliability**

D OR P PACKAGE
(TOP VIEW)

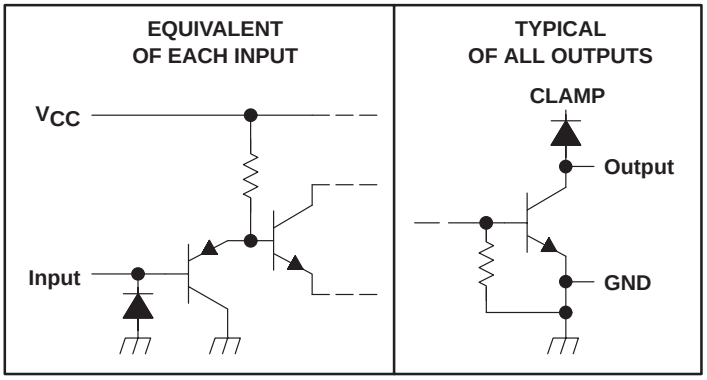


description

The SN75476 through SN75478 are dual peripheral drivers designed for use in systems that require high current, high voltage, and fast switching times. The SN75476, SN75477, and SN75478 provide AND, NAND, and OR drivers respectively. These devices have diode-clamped inputs as well as high-current, high-voltage clamp diodes on the outputs for inductive transient protection.

The SN75476, SN75477, and SN75478 drivers are characterized for operation from 0°C to 70°C.

schematics of inputs and outputs



Function Tables

SN75476
(each AND driver)

INPUTS		OUTPUT
A	S	Y
H	H	H
L	X	L
X	L	L

SN75477
(each NAND driver)

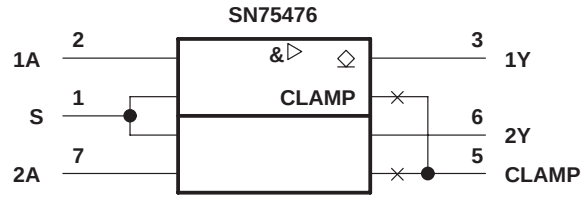
INPUTS		OUTPUT
A	S	Y
H	H	L
L	X	H
X	L	H

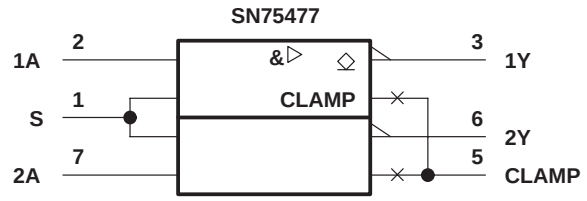
SN75478
(each OR driver)

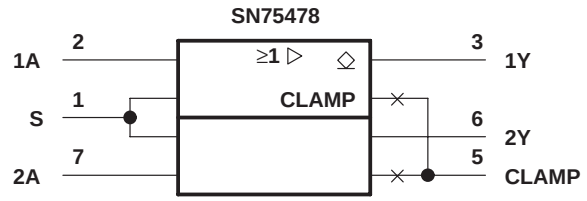
INPUTS		OUTPUT
A	S	Y
H	X	H
X	H	H
L	L	L

H = high level, L = low level
X = irrelevant

logic symbols†

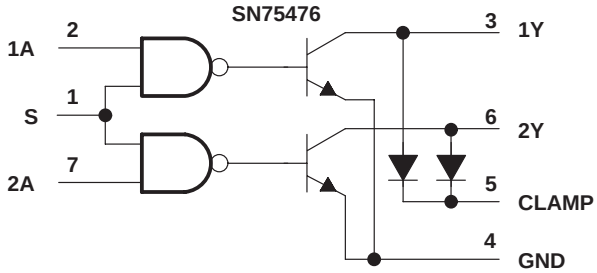




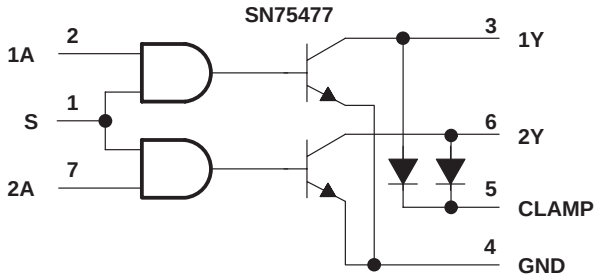


† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

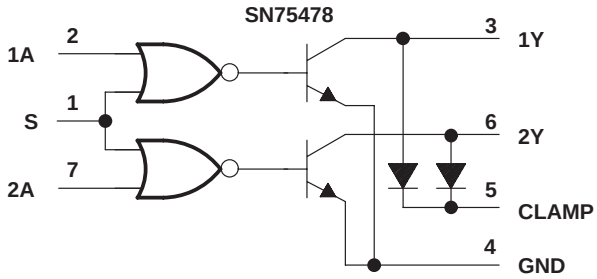
logic diagrams (positive logic)



Positive Logic: $Y = AS$ or $\overline{\overline{A}+\overline{S}}$



Positive Logic: $Y = \overline{AS}$ or $\overline{A}+\overline{S}$



Positive Logic: $Y = A+S$ or $\overline{\overline{A}\,\overline{S}}$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I . . . . . 5.5 V
Continuous output current (see Note 2) . . . . . 400 mA
Peak output current: $t_w \leq 10$ ms, duty cycle $\leq 50\%$ . . . . . 500 mA
$t_w \leq 30$ ns, duty cycle $\leq 0.002\%$ . . . . . 3 A
Output clamp current, I_{OK} . . . . . 400 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

NOTES: 1. Voltage values are with respect to network GND.
2. Both halves of this dual circuit may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous power dissipation ratings.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
P	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.5	5	5.5	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
Operating free-air temperature, T_A	0		70	°C

electrical characteristics over recommended operating free-air temperature range

PARAMETER			TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	Input clamp voltage		I_I = –12 mA			–0.95	–1.5	V
V_{OL}	Low-level output voltage		V_{CC} = 4.5 V, V_{IH} = 2 V, V_{IL} = 0.8 V	I_{OL} = 100 mA		0.16	0.3	V
				I_{OL} = 175 mA		0.22	0.5	
				I_{OL} = 300 mA		0.33	0.6	
$V_{O(BR)}$	Output breakdown voltage		V_{CC} = 4.5 V,	I_{OH} = 100 μA	70	100		V
$V_{R(K)}$	Output clamp reverse voltage		V_{CC} = 4.5 V,	I_R = 100 μA	70	100		V
$V_{F(K)}$	Output clamp forward voltage		V_{CC} = 4.5 V,	I_F = 300 mA	0.8	1.15	1.6	V
I_{OH}	High-level output current		V_{CC} = 4.5 V, V_{IL} = 0.8 V,	V_{IH} = 2 V, V_{OH} = 70 V		1	100	μA
I_{IH}	High-level input current		V_{CC} = 5.5 V,	V_I = 5.5 V		0.01	10	μA
I_{IL}	Low-level input current	A input	V_{CC} = 5.5 V,	V_I = 0.8 V		–80	–110	μA
		S input				–160	–220	
I_{CCH}	Supply current, outputs high	SN75476	V_{CC} = 5.5 V	V_I = 5 V		10	17	mA
		SN75477		V_I = 0		10	17	
		SN75478		V_I = 5 V		10	17	
I_{CCL}	Supply current, outputs low	SN75476	V_{CC} = 5.5 V	V_I = 0		54	75	mA
		SN75477		V_I = 5 V		54	75	
		SN75478		V_I = 0		54	75	

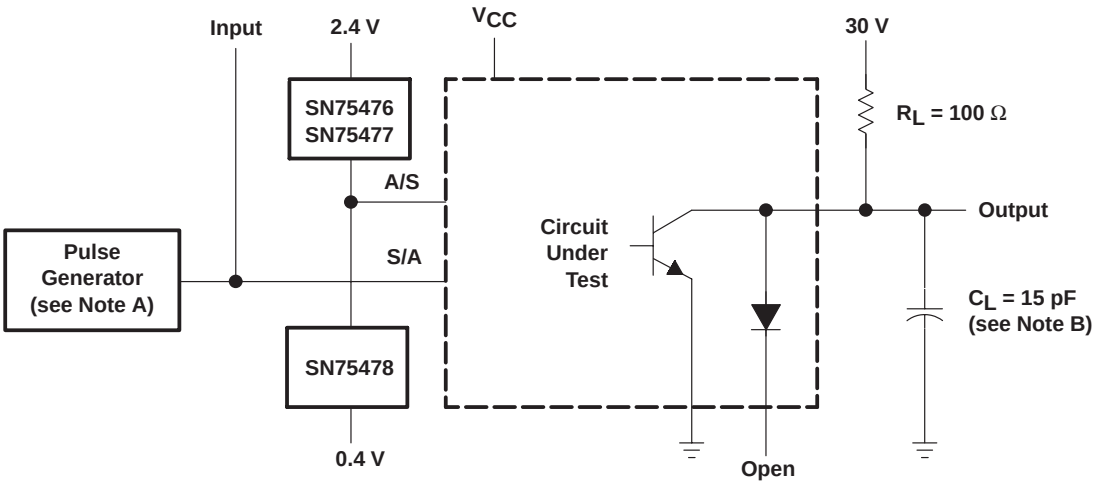
† All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

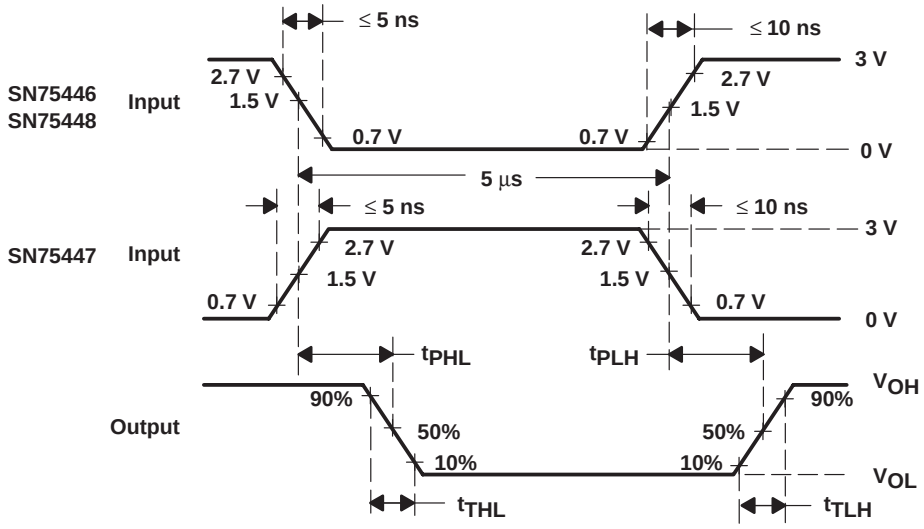
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	C_L = 15 pF, See Figure 1	R_L = 100 Ω,		200	350	ns
t_{PHL}	Propagation delay time, high-to-low-level output				200	350	ns
t_{TLH}	Transition time, low-to-high-level output				50	125	ns
t_{THL}	Transition time, high-to-low-level output				90	125	ns
V_{OH}	High-level output voltage after switching	V_S = 55 V, See Figure 2	I_O ≈ 300 mA,	V_S–18			mV

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251–1443

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

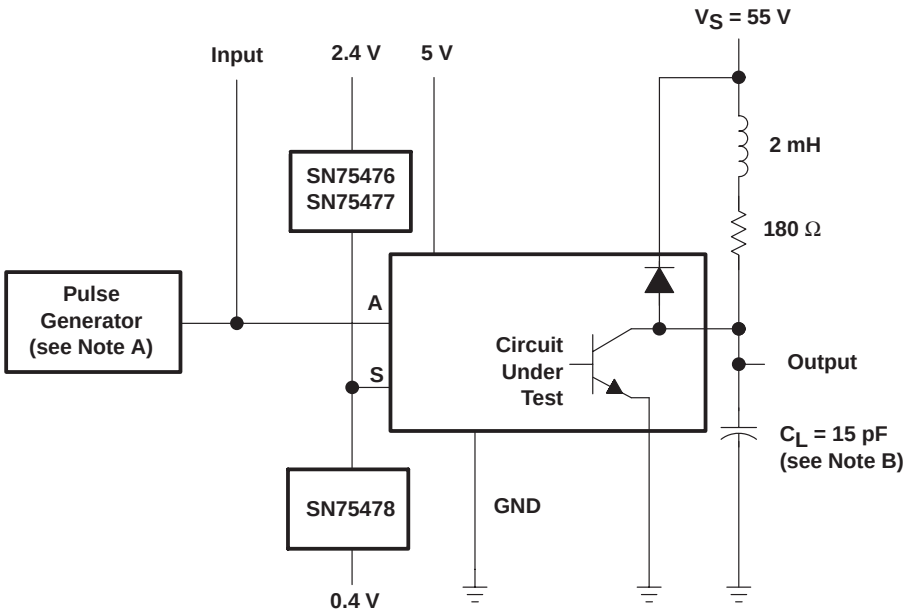


VOLTAGE WAVEFORMS

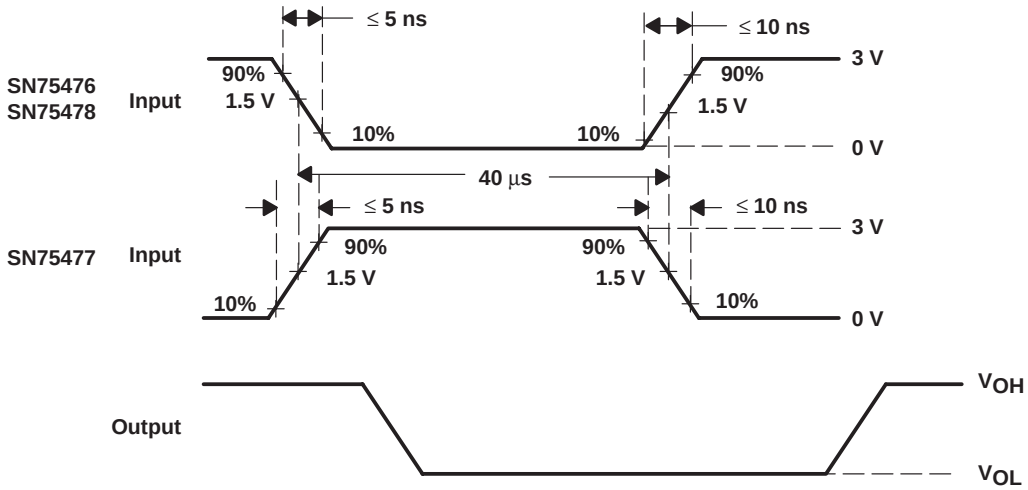
NOTES: A. The pulse generator has the following characteristics: PRR = 100 kHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms, Switching Characteristics

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 2. Latch-Up Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75477D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DE4	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DG4	ACTIVE	SOIC	D	8	75	TBD	Call TI	Call TI	0 to 70		Samples
SN75477DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477DRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75477	Samples
SN75477P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75477P	Samples
SN75477PE4	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75477P	Samples
SN75478P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75478P	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

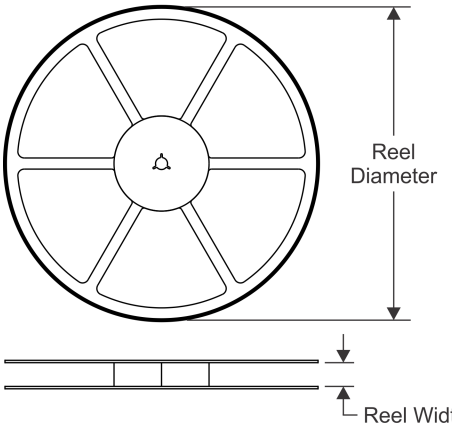
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

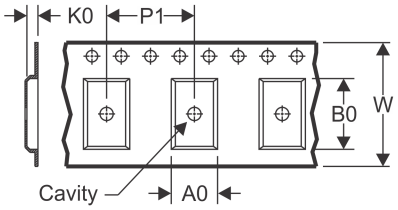
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

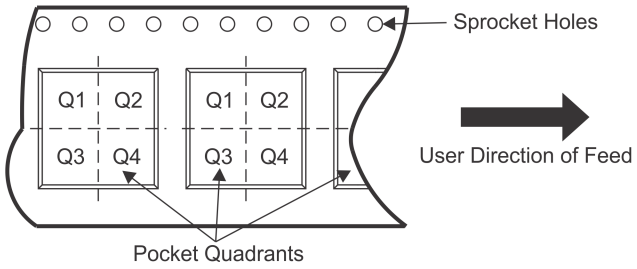


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

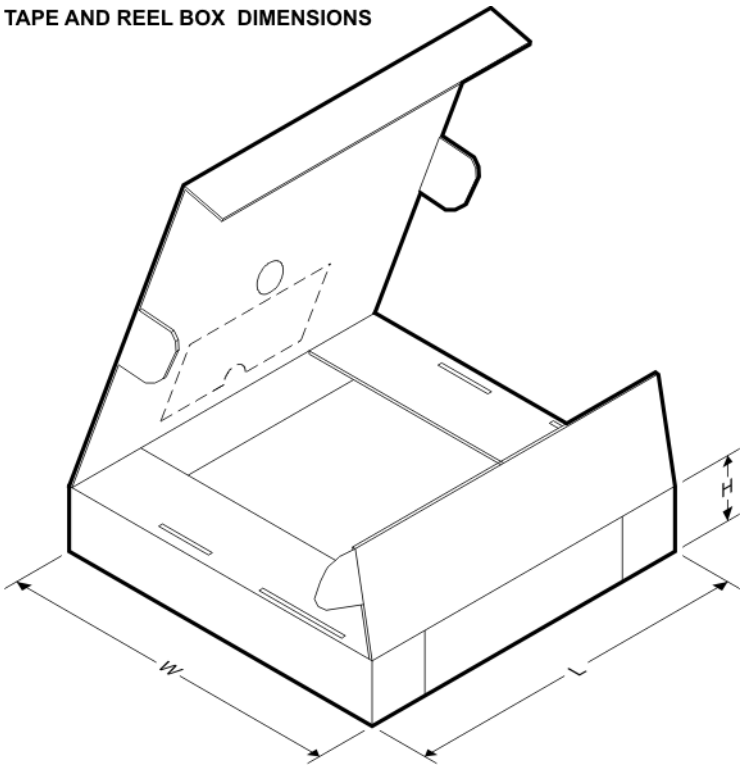
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75477DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

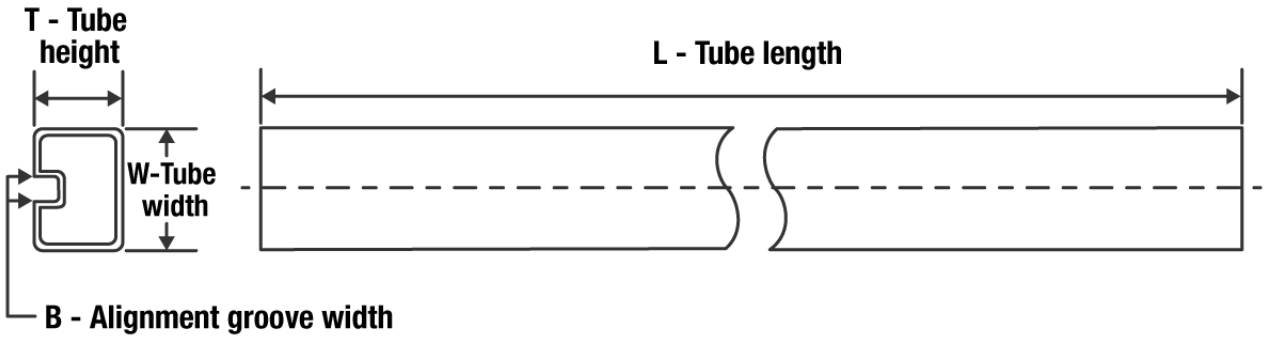
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

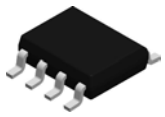
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75477DR	SOIC	D	8	2500	340.5	336.1	25.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75477D	D	SOIC	8	75	507	8	3940	4.32
SN75477DE4	D	SOIC	8	75	507	8	3940	4.32
SN75477DG4	D	SOIC	8	75	507	8	3940	4.32
SN75477P	P	PDIP	8	50	506	13.97	11230	4.32
SN75477PE4	P	PDIP	8	50	506	13.97	11230	4.32
SN75478P	P	PDIP	8	50	506	13.97	11230	4.32

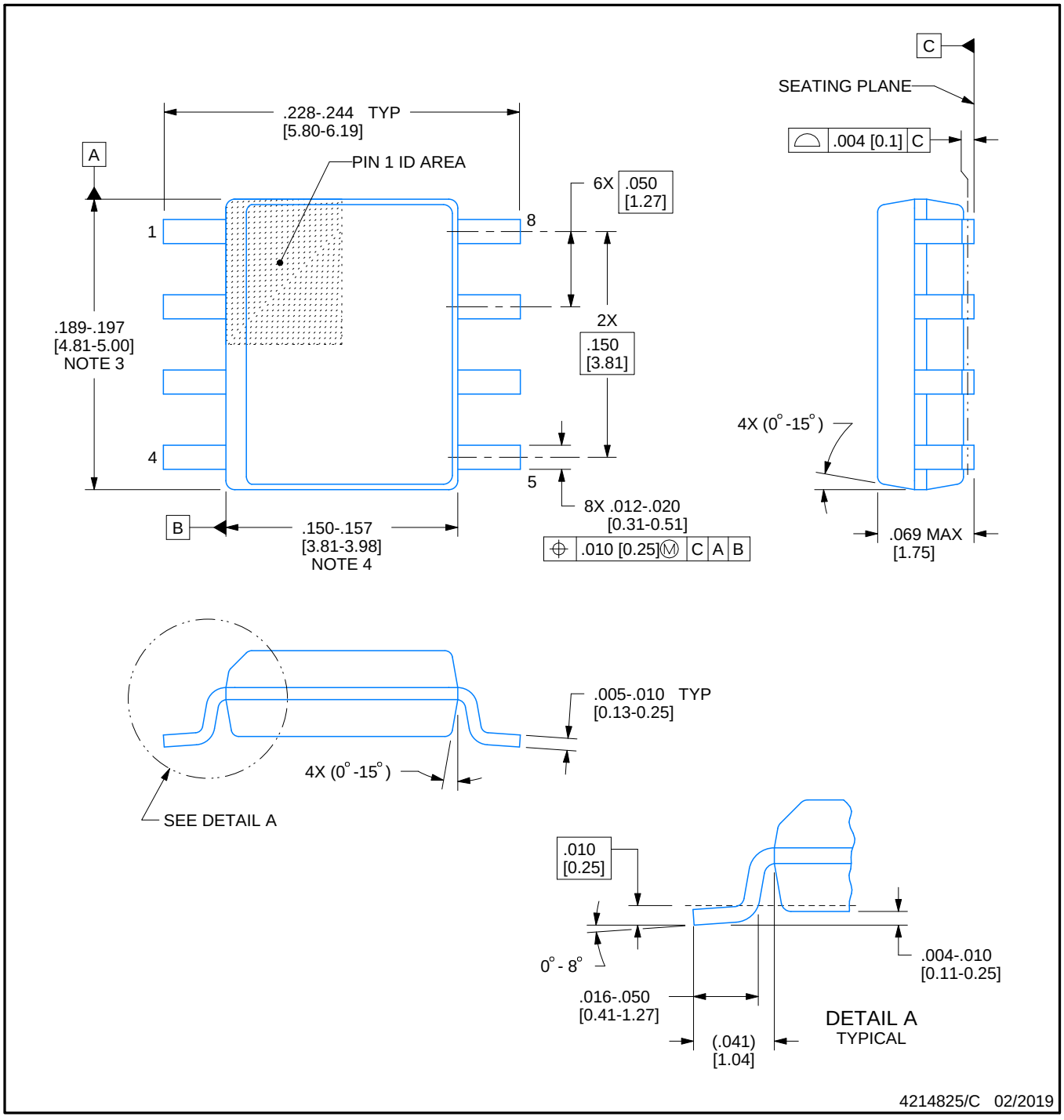


PACKAGE OUTLINE

D0008A

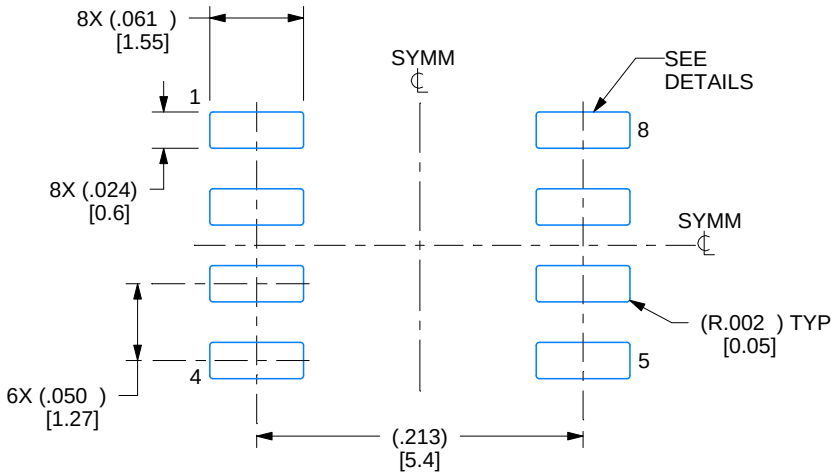
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

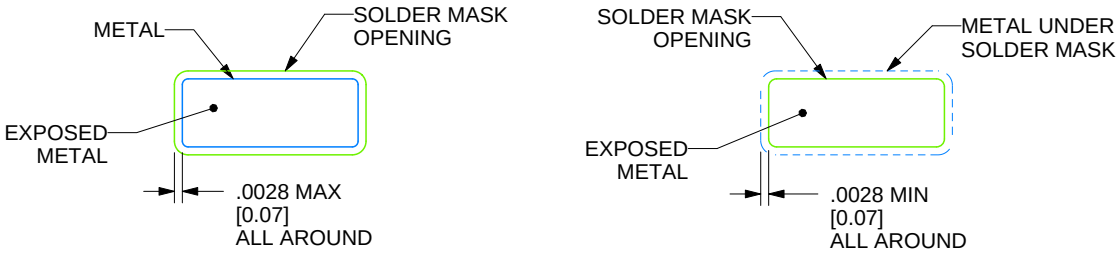


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

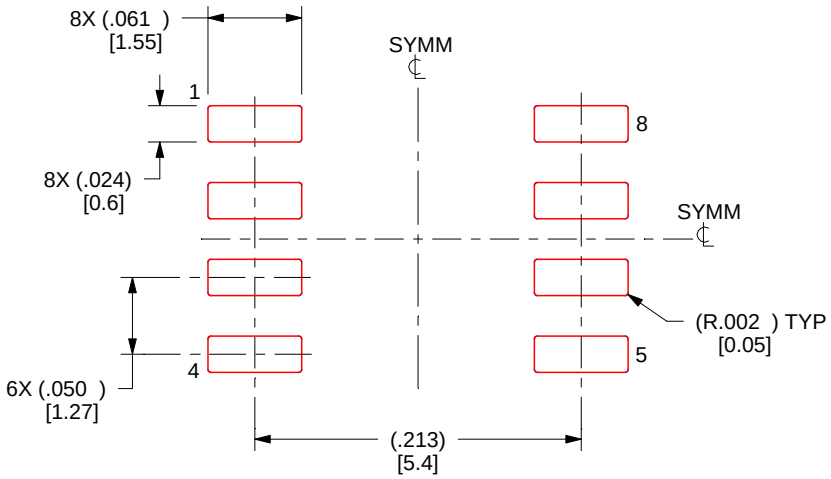
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



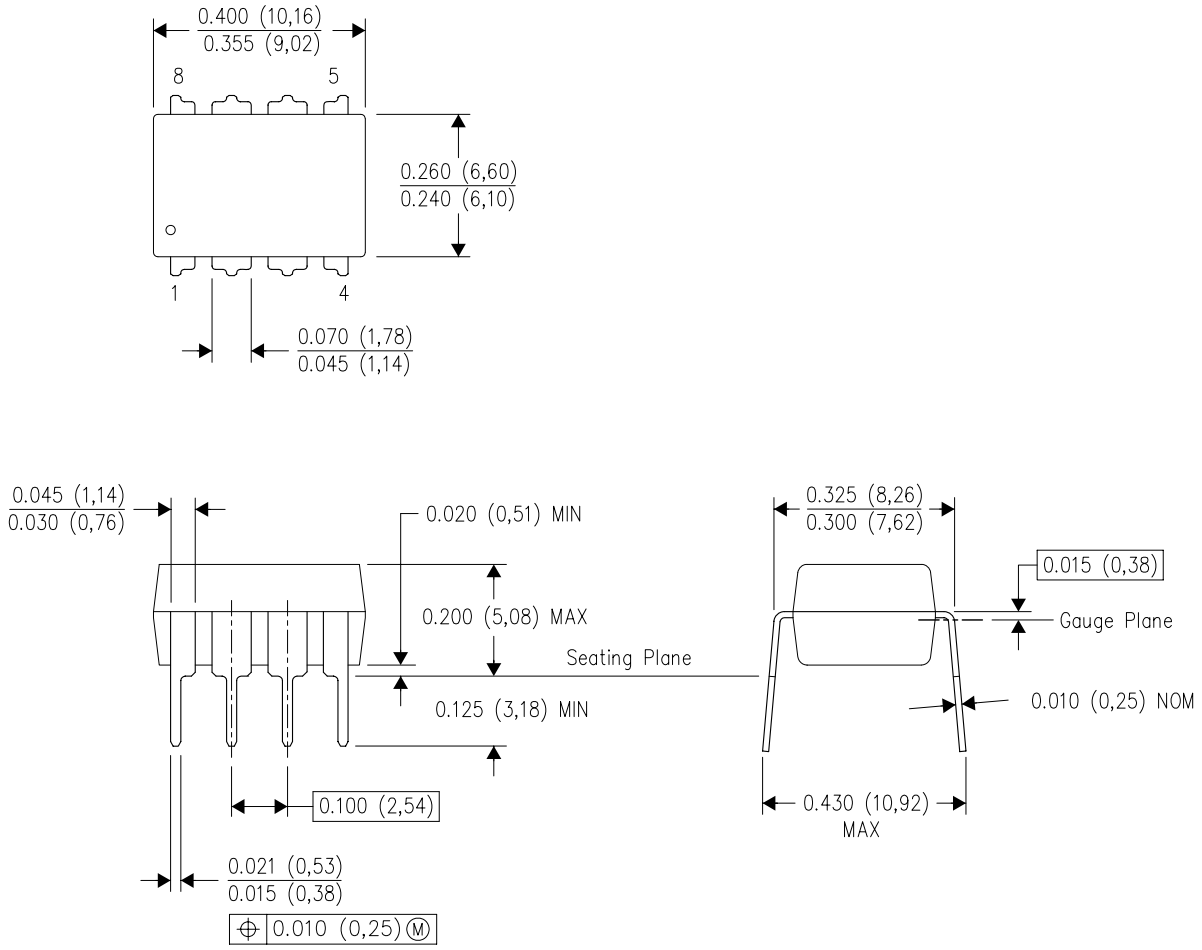
SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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